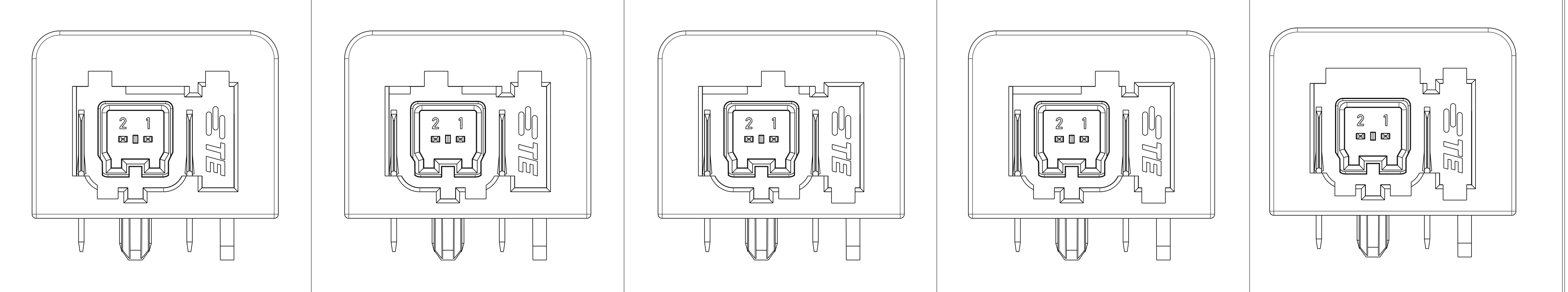


2304372-1 COD. A AS SHOWN wie gezeichnet

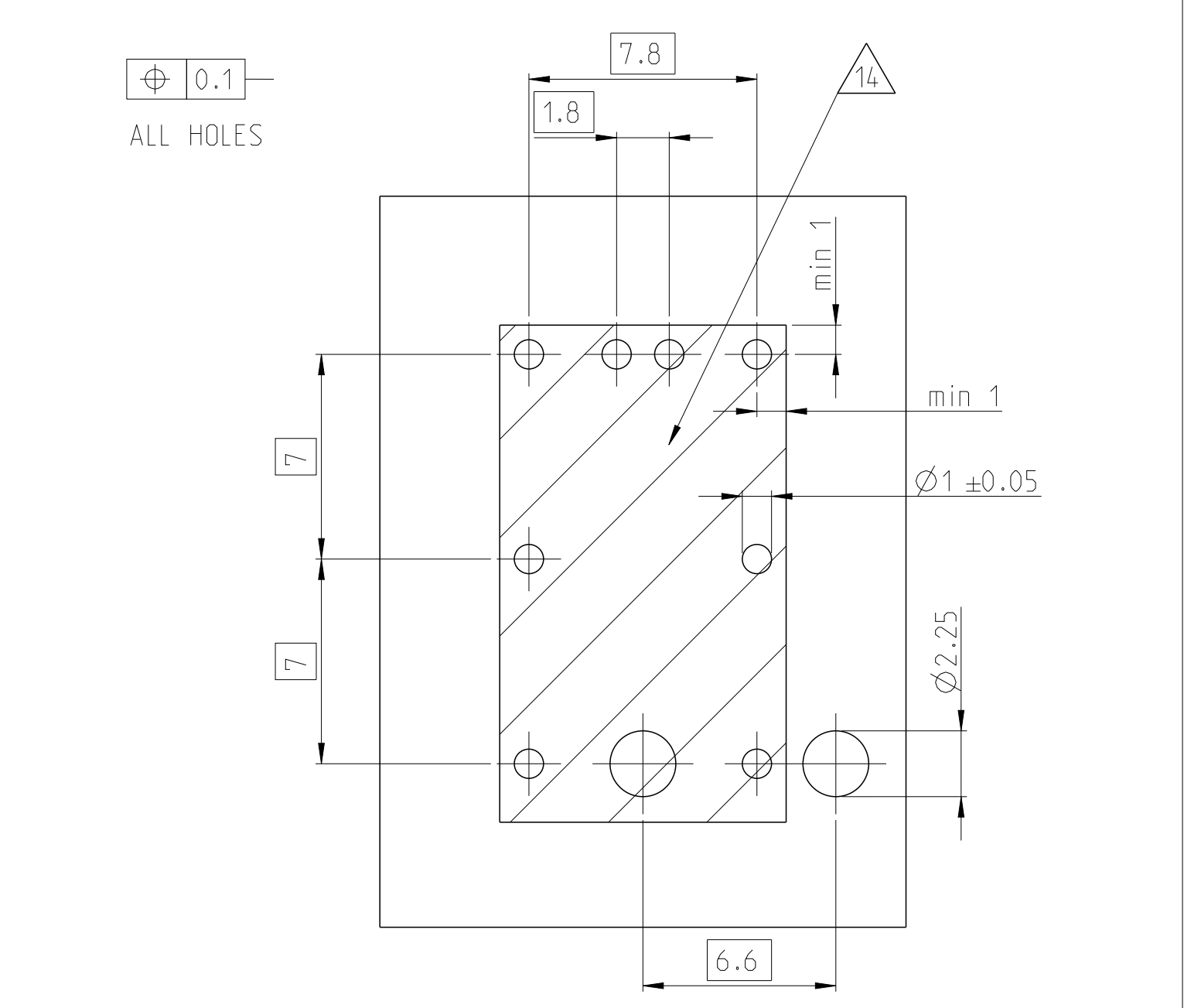
REVISIONS			
REV	DATE	BY	APPD
A1	30NOV2016	AB	AB
A2	14SEP2017	MSA	AB

- NOTES
Bemerkungen
- PRESS OUT FORCE FOR NANOMQS CONTACT >15N WITH FEED RATE 25mm/min
Kontaktdruckkraft fuer NanoMQS Kontakt >15N mit Vorschubgeschwindigkeit 25mm/min
 - INTERFACES ACC. TO 208-18010, REV. A1, 06. JUN 2016
Schnittstellen nach 208-18010, Rev.A1 vom 06.06.2016
 - SOLDERING PROCESS: LEAD-FREE REFLOW SOLDERING IN REFERENCE TO JEDEC J-STD-020D
Loetprozess: Bleifreies Loeten in Anlehnung an die JEDEC J-STD-020D
 - TOLERANCES ACC. TO DIN EN ISO 8015, DIN EN ISO 14405-1
GENERAL TOL. ACC. TO DIN 16742 T65, EXCEPT ANGLE DIM. (SEE TITLE BLOCK)
Tolerierung nach DIN EN ISO 8015, DIN EN ISO 14405-1
Allgemeintoleranzen nach DIN 16742 T65, ausser Winkelmasse (siehe Schriftkopf)
 - PACKAGING IN TAPE & REEL ACC. TO V2304372
Verpackung in Tape & Reel nach V2304372
 - CONTACT SURFACE SOLDER SIDE 3-8µm Sn OVER 1-2.5µm Ni
Kontaktoberflaeche Lotseitig 3-8µm Sn ueber 1-2.5µm Ni
 - FOR MISSING DIMENSION SEE CAD-MODEL 2305390-X, REV. A
Fehlende Masse sind dem CAD-Model 2305390-X, Rev. A zu entnehmen
 - GOOD PART MARKING PUNCH MARKED
Gutteilmarkierung Koernerpunkt
 - ELECTRICAL 100% FINAL INSPECTION FOR CONTINUITY AND SHORT CIRCUIT
AS WELL AS EXISTENCE OF ALL CONTACTS
Elektrische 100% Endpruefung auf Durchgang und Kurzschluss,
sowie das Vorhandensein aller Kontakte
 - VACUUM GRIP AREA FREE OF BURR AND EJECTOR PINS
Ansaugflaeche frei von Grat und Auswerferstiften
 - COLOURED IDENTIFICATION MARK FOR C-SAMPLES tbd
Farbliche Markierung fuer C-Muster
 - HEADER FULFILL RF-REQUIREMENTS UP TO 10GHz ACC. TE SPEC. 108-94509. ALSO MANDATORY IS A PCB COPPER LAYER ACC. TO TE SPEC. 114-94448
Der Header erfuehlt die RF-Anforderungen bis zu 1 GHz nach TE Spez. 108-94509. Ebenfalls notwendig ist eine Leiterplatten Kupferschicht nach TE Spez. 114-94448
 - HEADER FULFILL RF-REQUIREMENTS UP TO 100 Mhz ACC. TE SPEC 108-94444
Der Header erfuehlt die RF-Anforderungen bis zu 100MHz nach TE Spez.108-94444
 - APPLICATION SPECIFICATION ACC. TO 114-94448
Anwendungsspezifikation TE Spez. 114-94448

2304372-1_COD_A AS SHOWN wie gezeichnet 2304372-2_COD_B AS SHOWN wie gezeichnet 2304372-3_COD_C AS SHOWN wie gezeichnet 2304372-7_COD_J AS SHOWN wie gezeichnet 2304372-9_COD_Z AS SHOWN wie gezeichnet



RECOMMENDED PCB LAYOUT / Empfohenes PCB Layout
CUSTOMER IS RESPONSIBLE FOR LAYOUT / Kunde ist fuers Layout verantwortlich



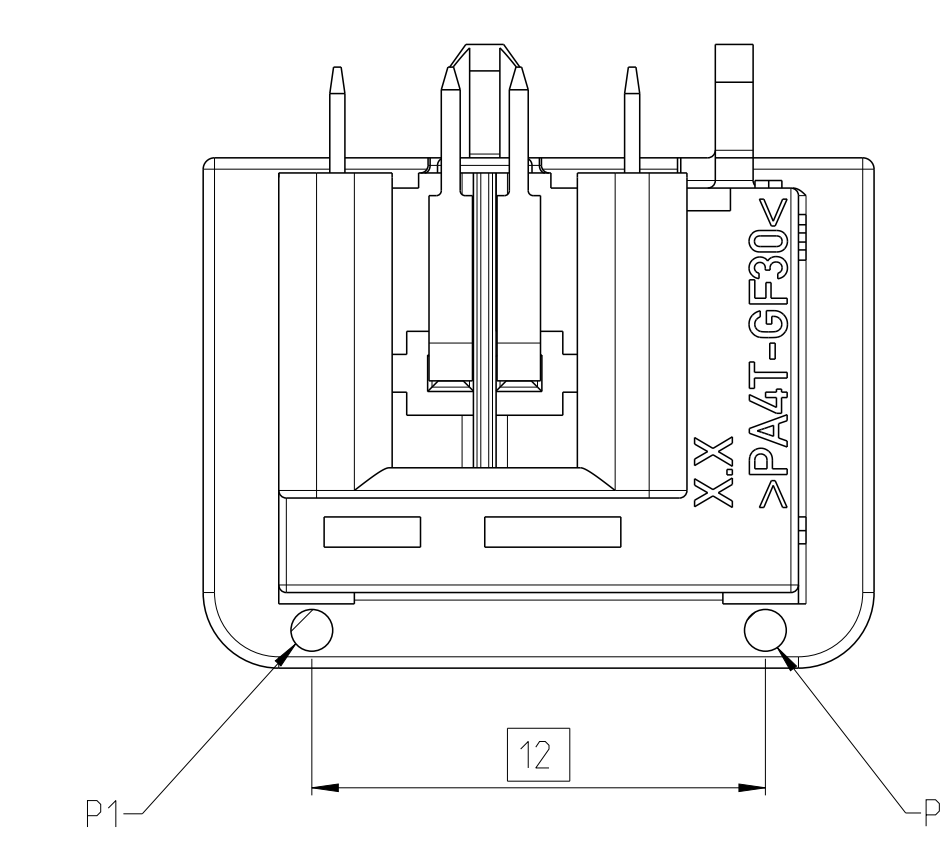
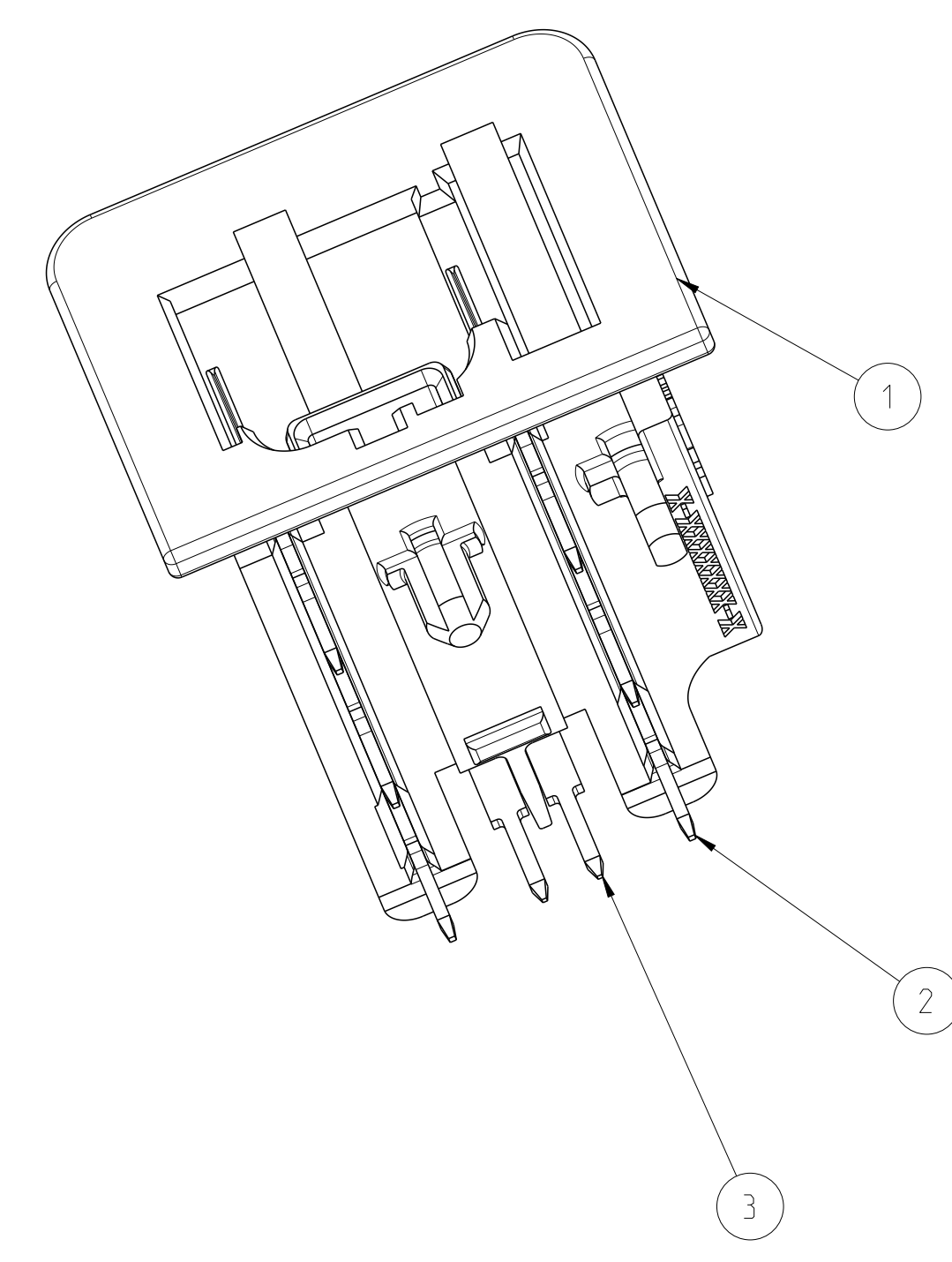
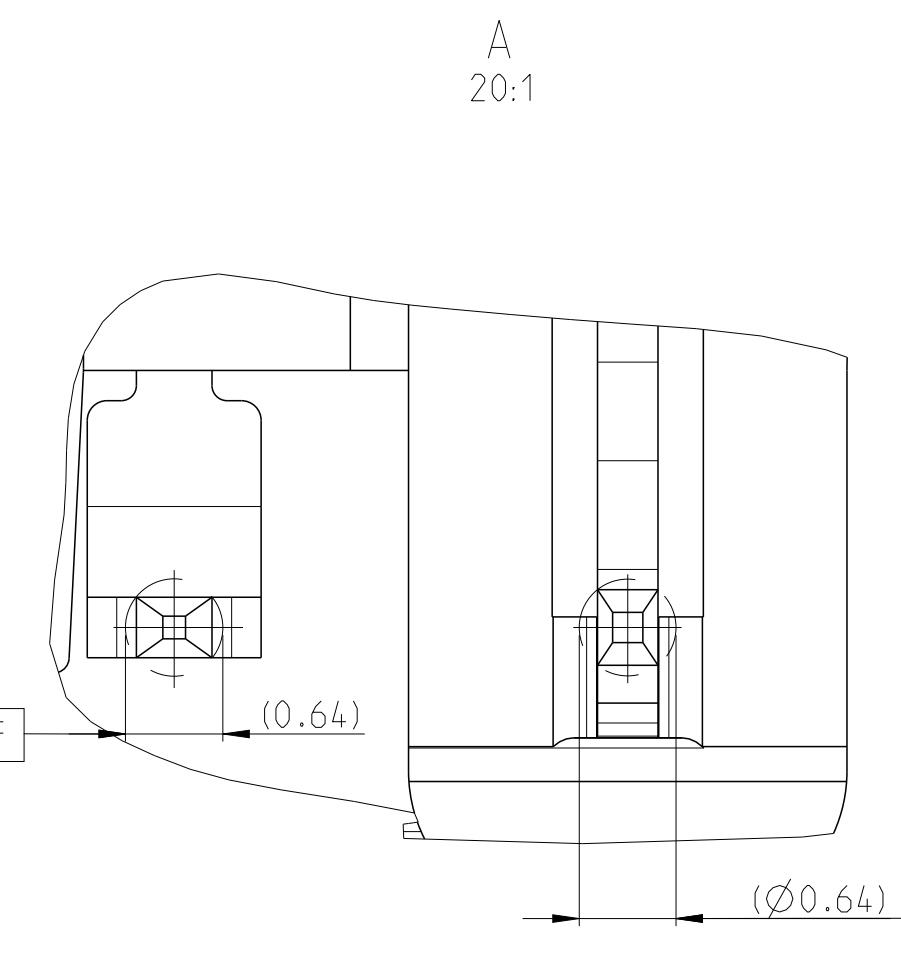
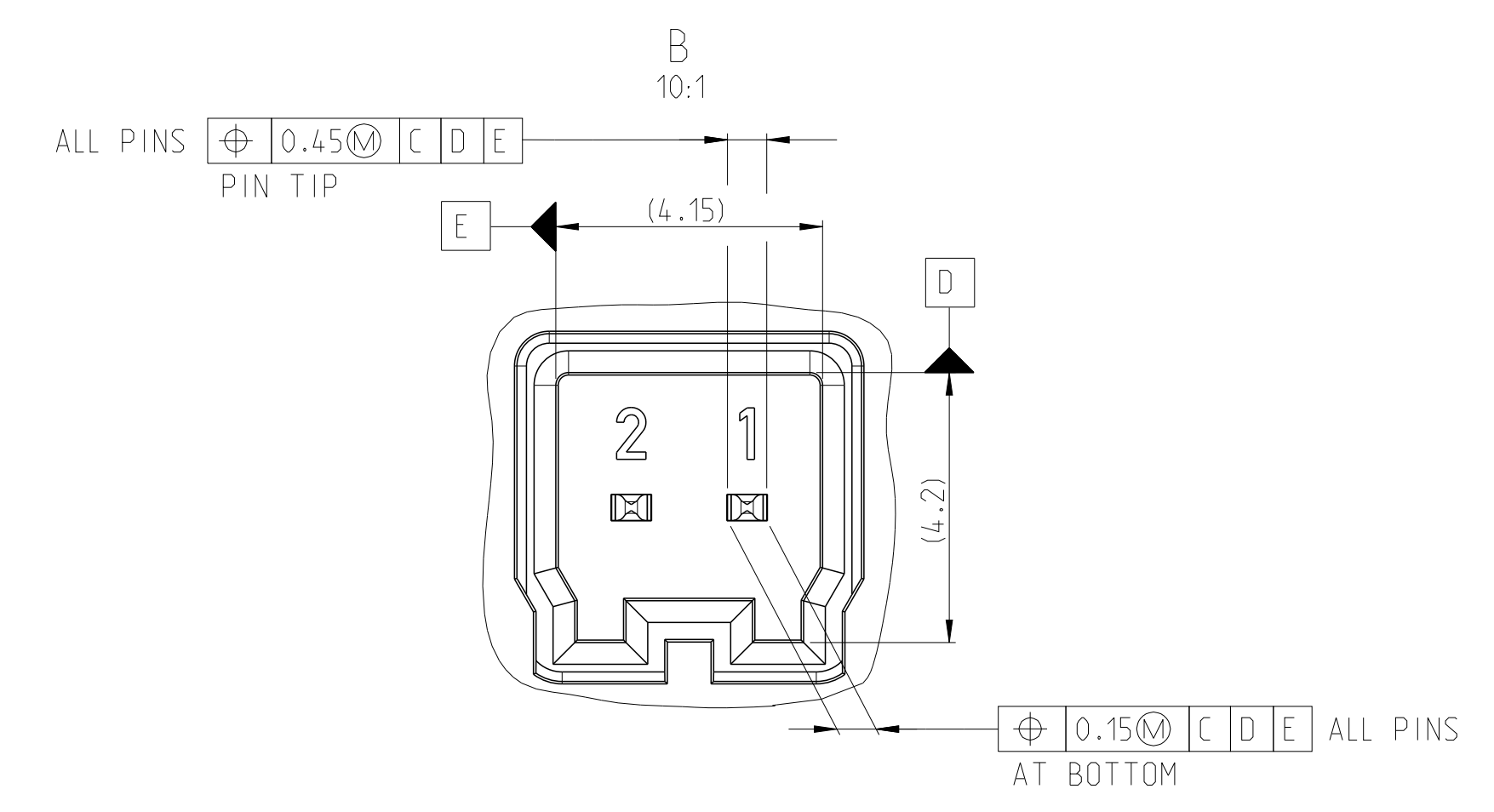
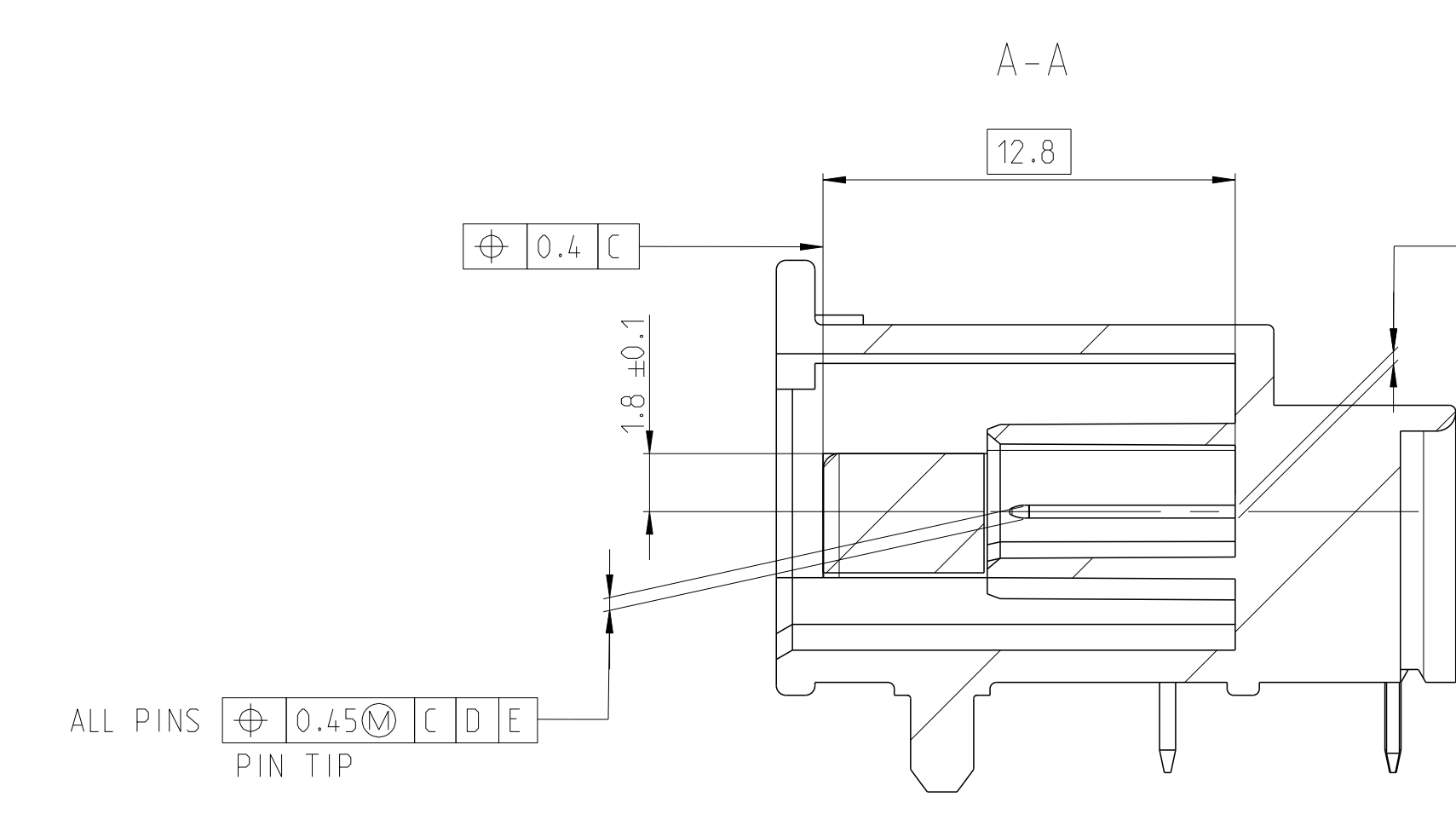
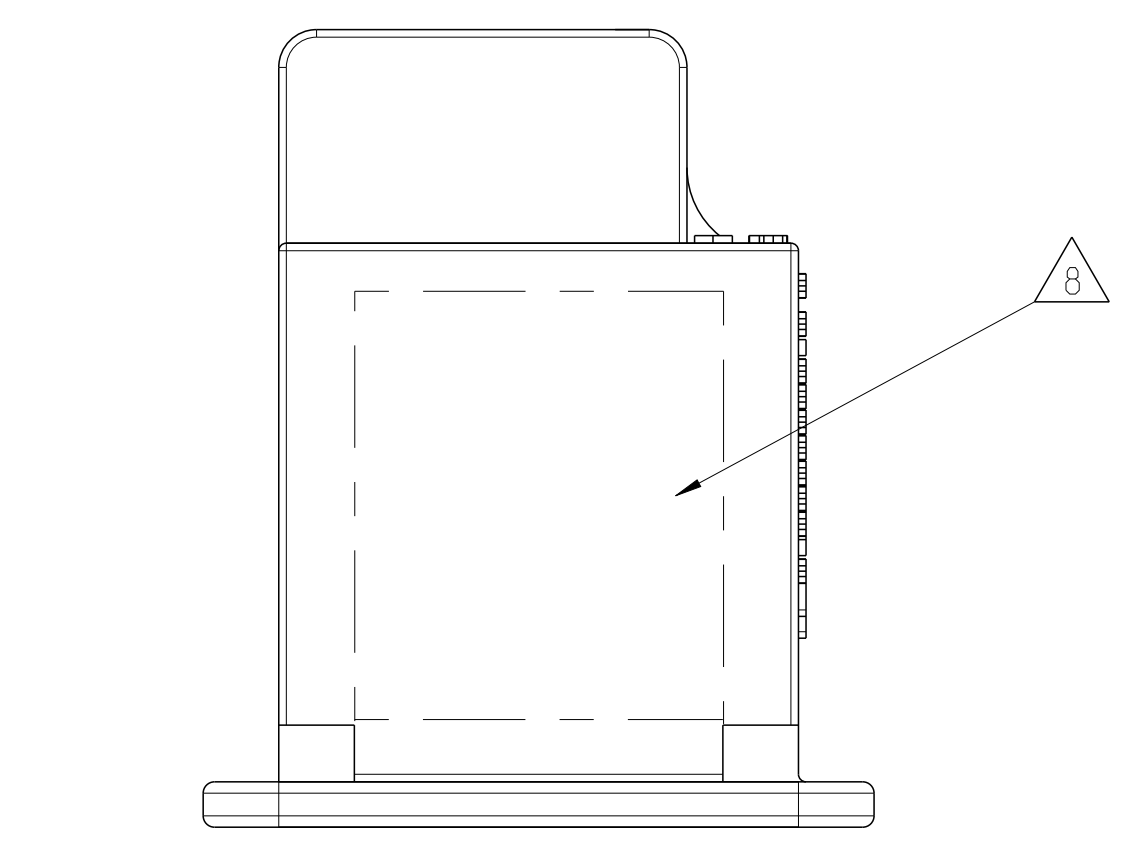
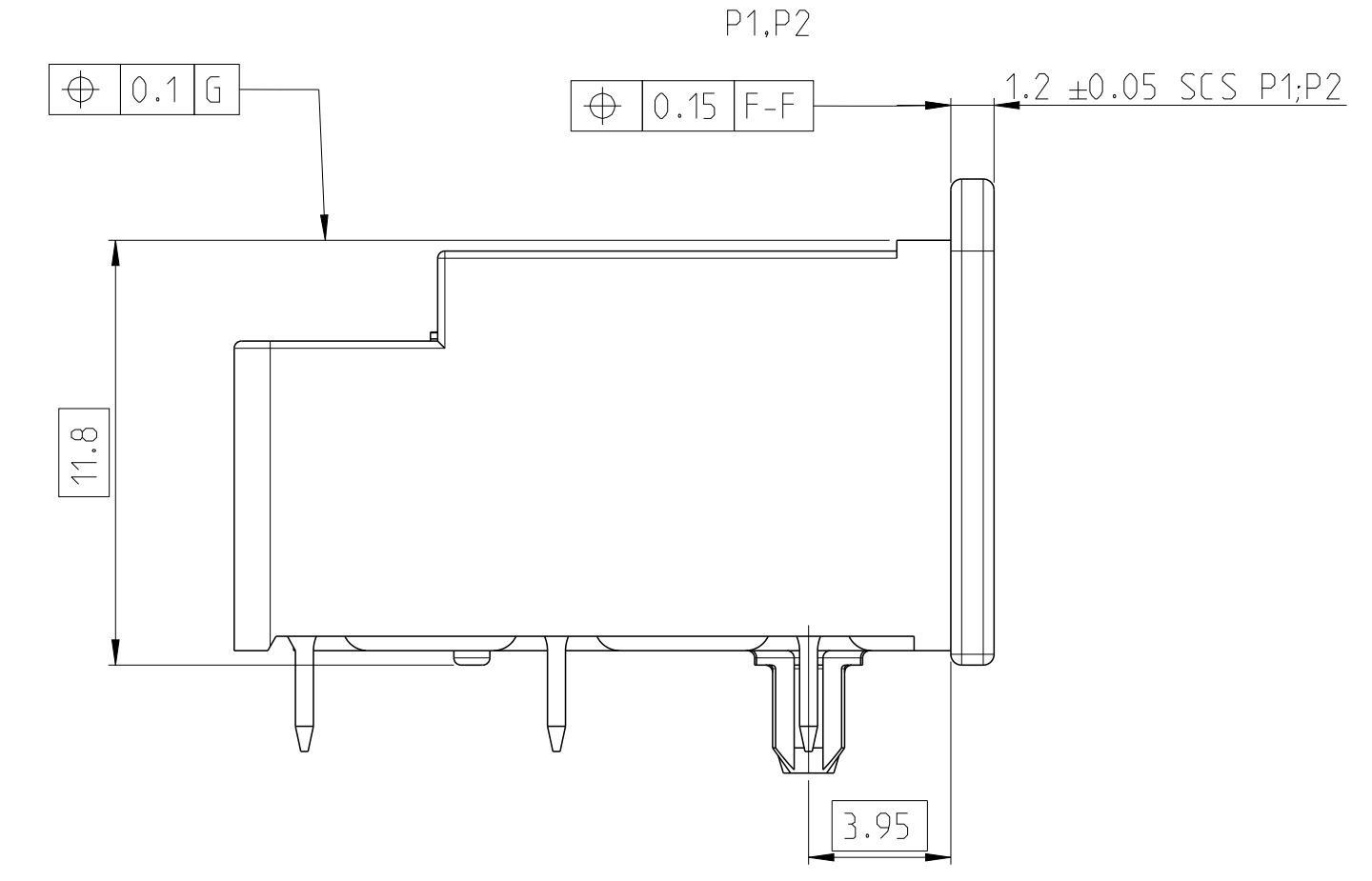
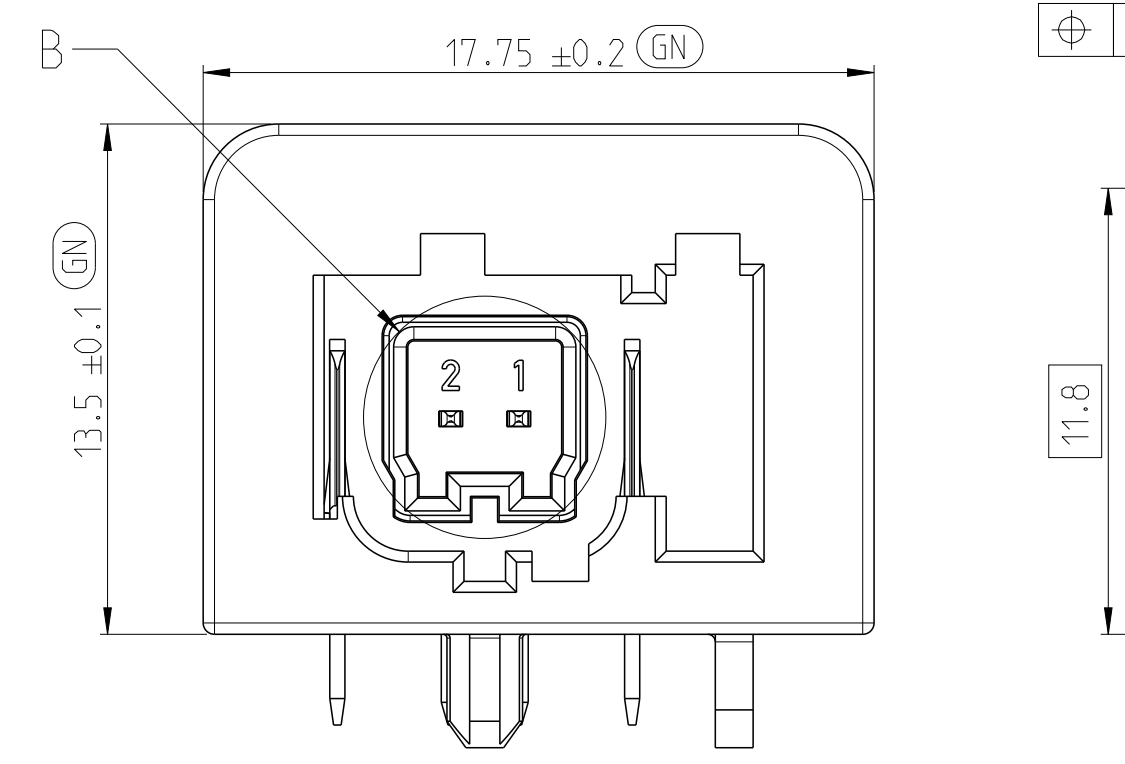
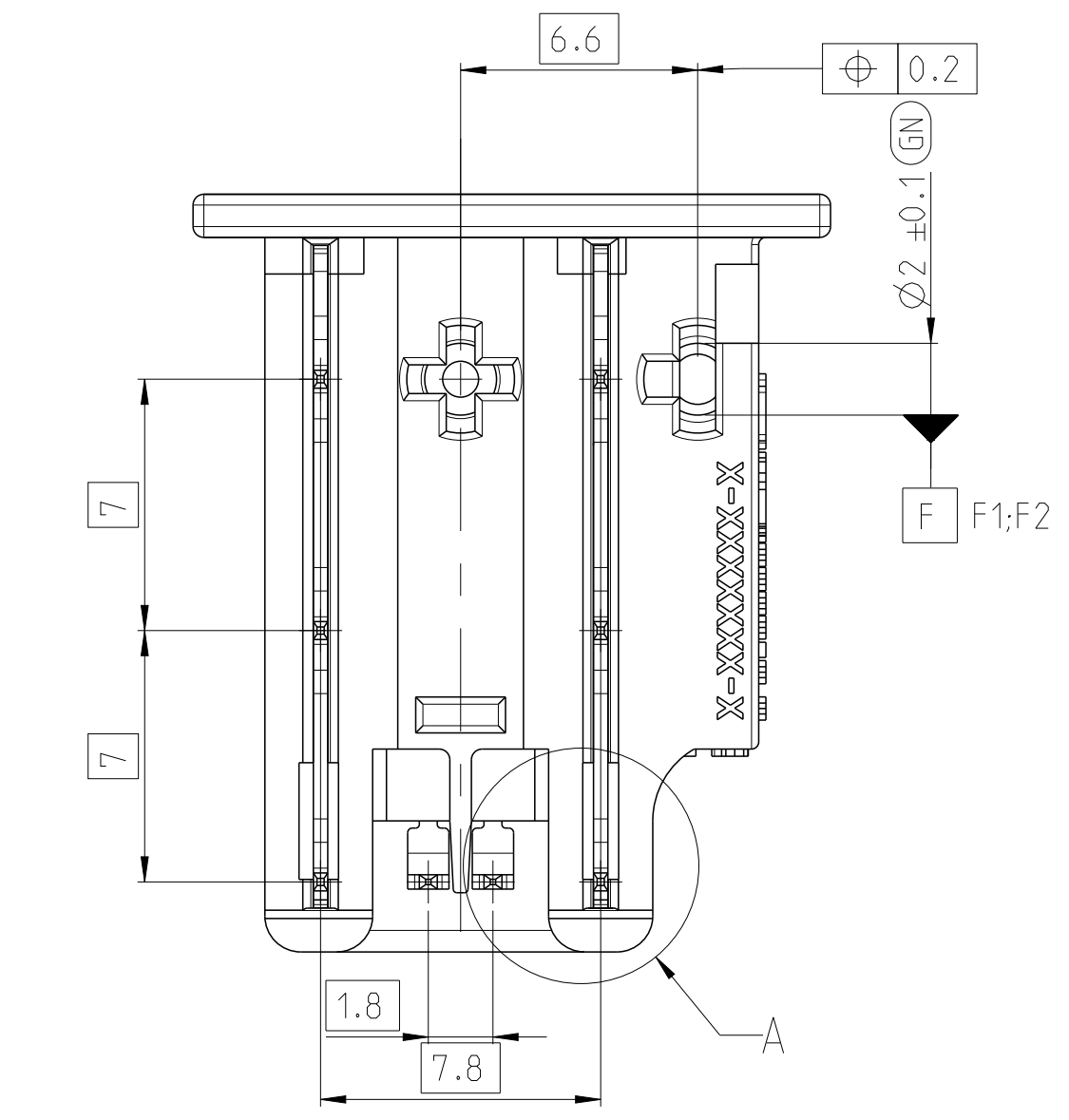
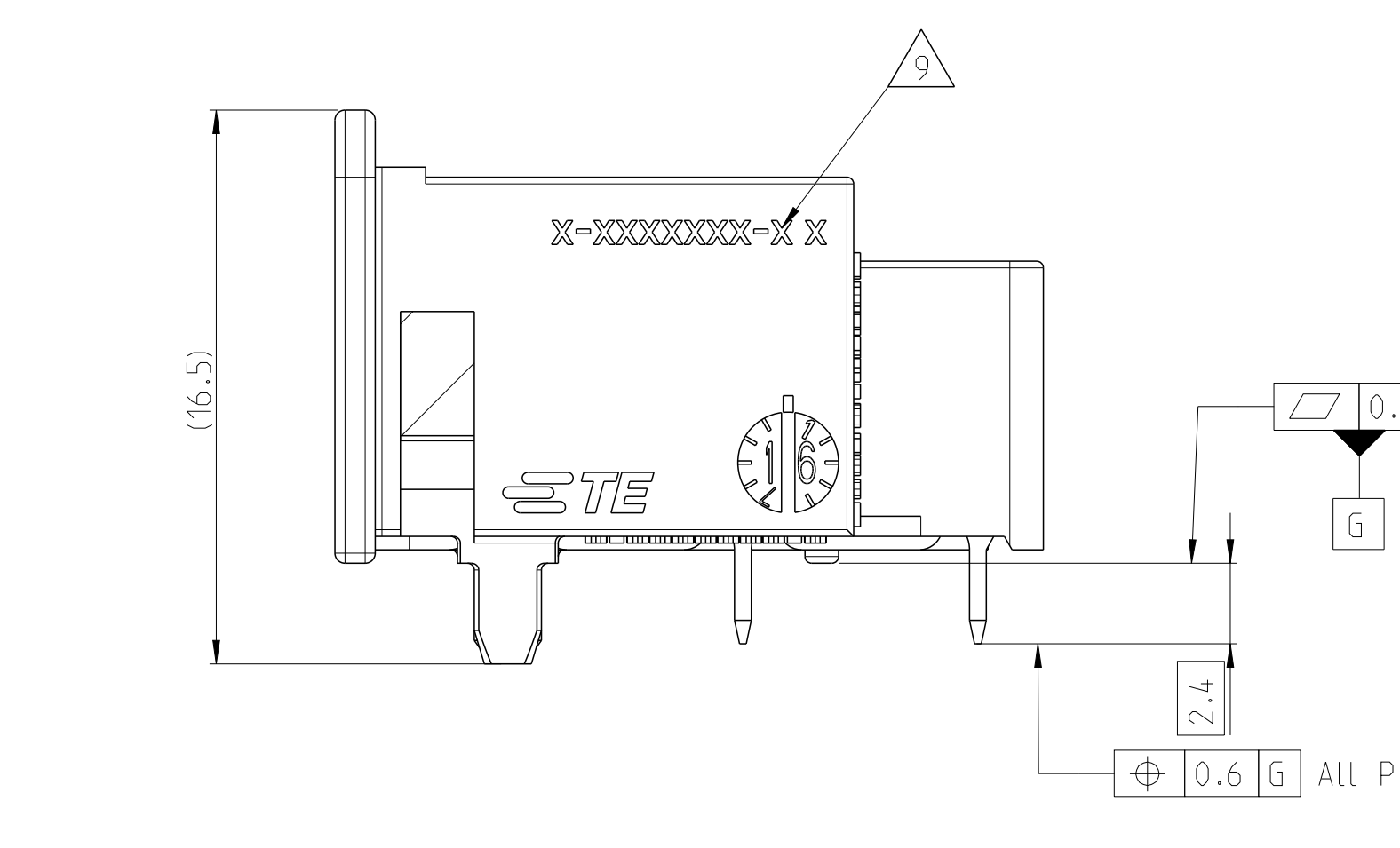
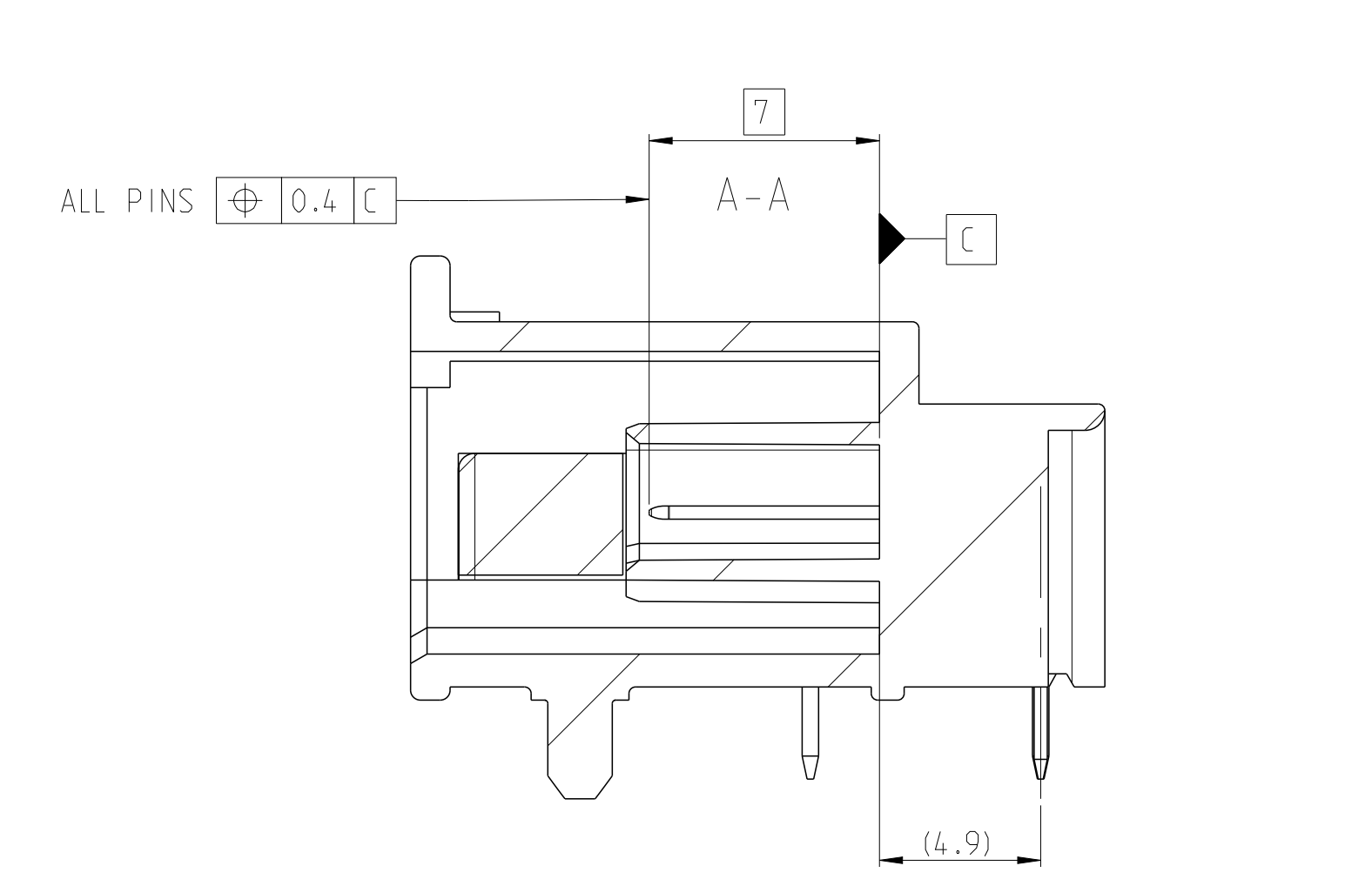
- 100% Inspection / 100% Pruefung
- Cmk= 1.67
- Cmk= 1.67
- GAUGE INSPECTION / Lehren Pruefung

TE ORDER NO.	WEIGHT(g)	CODING	REV	QTY.	DESCRIPTION	MATERIAL	POS.
2304372-9	2.7	Z	A	2	Nano MQS TAB 90°Sn	Cu-Alloy	3
				2	Shield	Cu-Alloy	2
				1	1 Part 90° HSG COD.Z	PA&T-GF30	1
2304372-7	2.98	J	A	2	Nano MQS TAB 90°Sn	Cu-Alloy	3
				2	Shield	Cu-Alloy	2
				1	1 Part 90° HSG COD.J	PA&T-GF30	1
2304372-3	2.98	C	A	2	Nano MQS TAB 90°Sn	Cu-Alloy	3
				2	Shield	Cu-Alloy	2
				1	1 Part 90° HSG COD.C	PA&T-GF30	1
2304372-2	2.98	B	A	2	Nano MQS TAB 90° Sn	Cu-Alloy	3
				2	Shield	Cu-Alloy	2
				1	1 Part 90° HSG COD.B	PA&T-GF30	1
2304372-1	2.98	A	A	2	Nano MQS TAB 90° Sn	Cu-Alloy	3
				2	Shield	Cu-Alloy	2
				1	1 Part 90° HSG COD.A	PA&T-GF30	1

THIS DRAWING IS A CONTROLLED DOCUMENT. DATE: 03JUN2016. BY: J. Burkhard. CH: J. Burkhard. 03JUN2016.

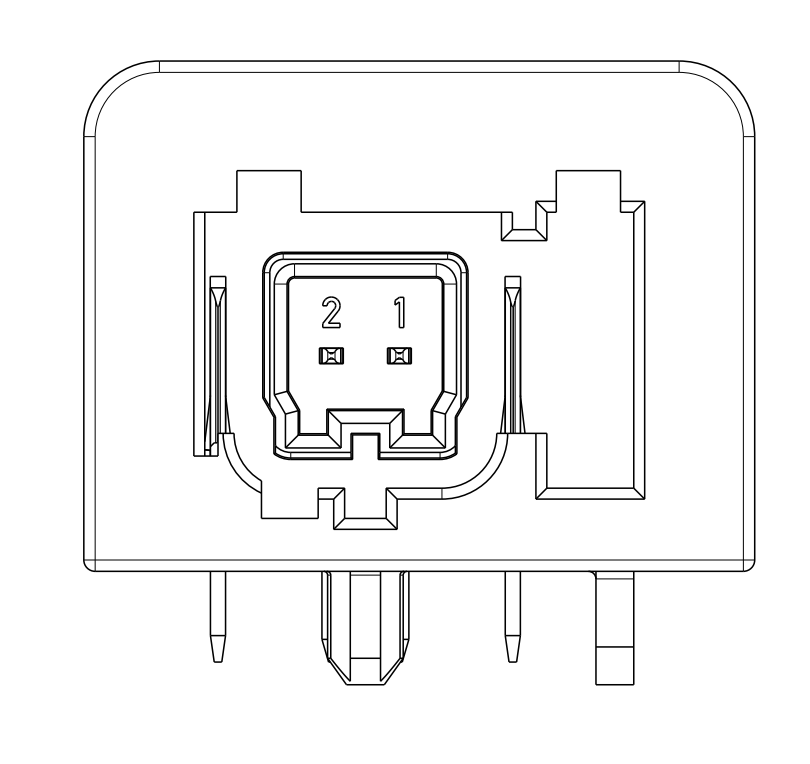
STANDARD: HSG COD. PRODUCT SPEC: 1 PORT HEADER ASSY. APPLICATION SPEC: 1 Part Header ASSY.

MATERIAL: PA&T-GF30. WEIGHT: -. SIZE: A0. CASE CODE: 00779. DRAWING NO: 2304372. RESTRICTED TO: -. SCALE: 5:1. SHEET: 1 of 3. REV: A2.

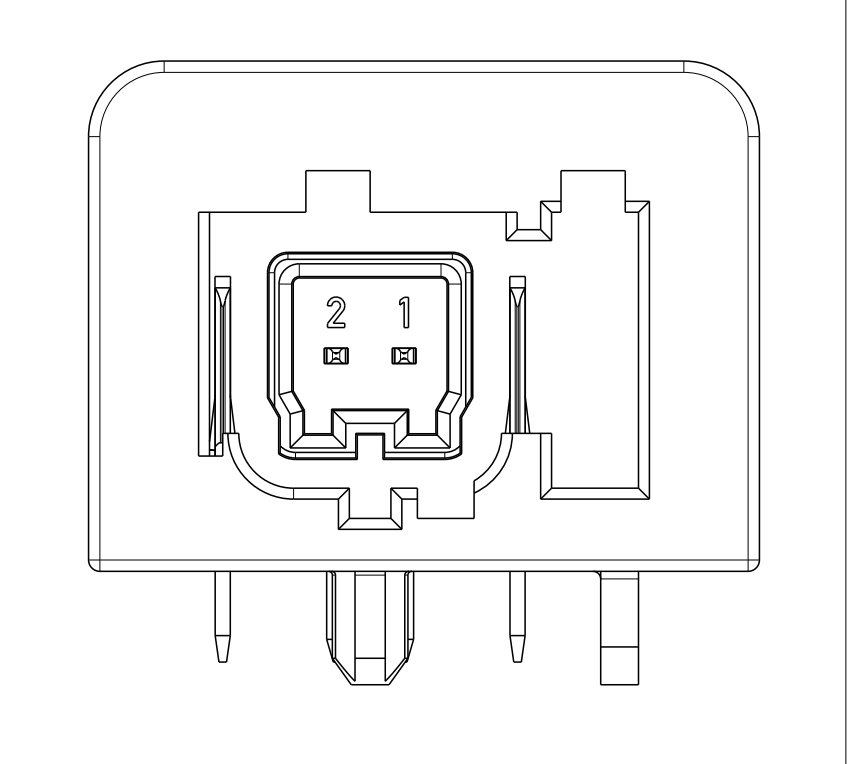


FOR PILOT ONLY
Nur fuer PILOT.

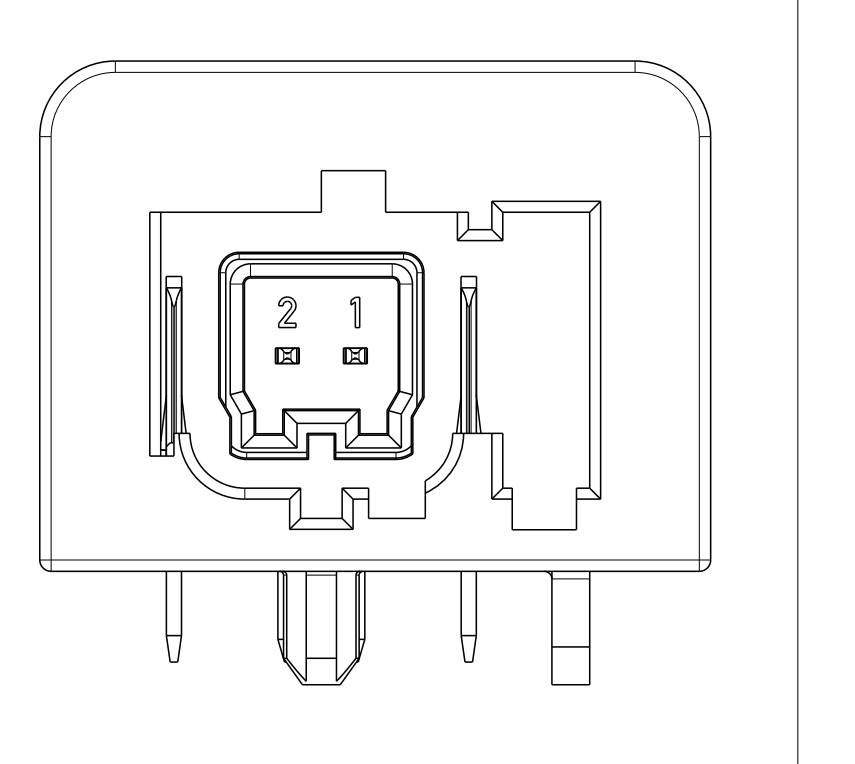
9-2304372-1_COD_A AS SHOWN wie gezeichnet



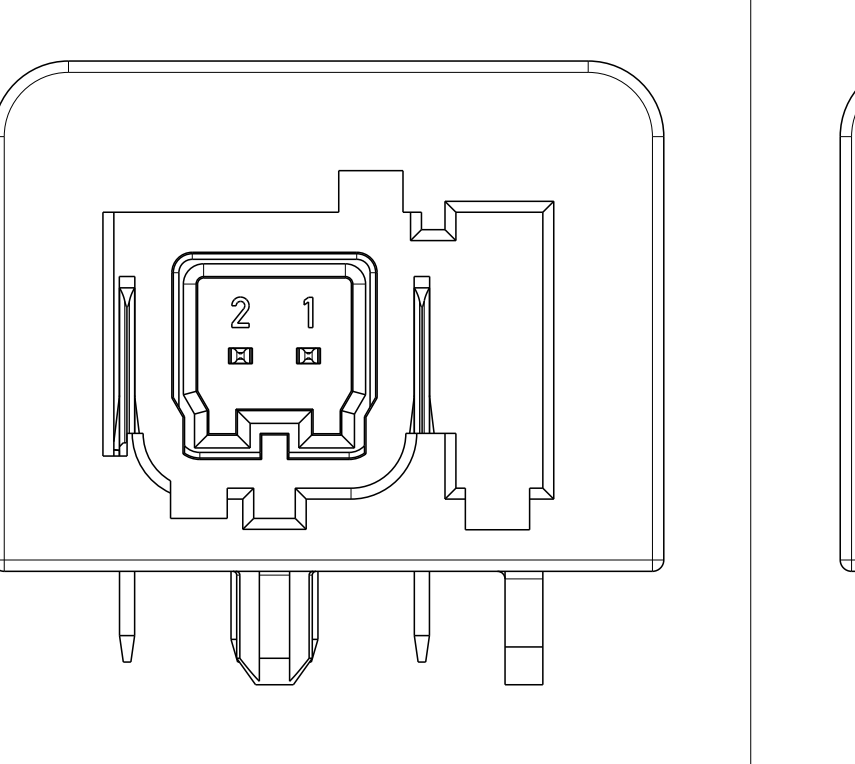
9-2304372-2_COD_B AS SHOWN wie gezeichnet



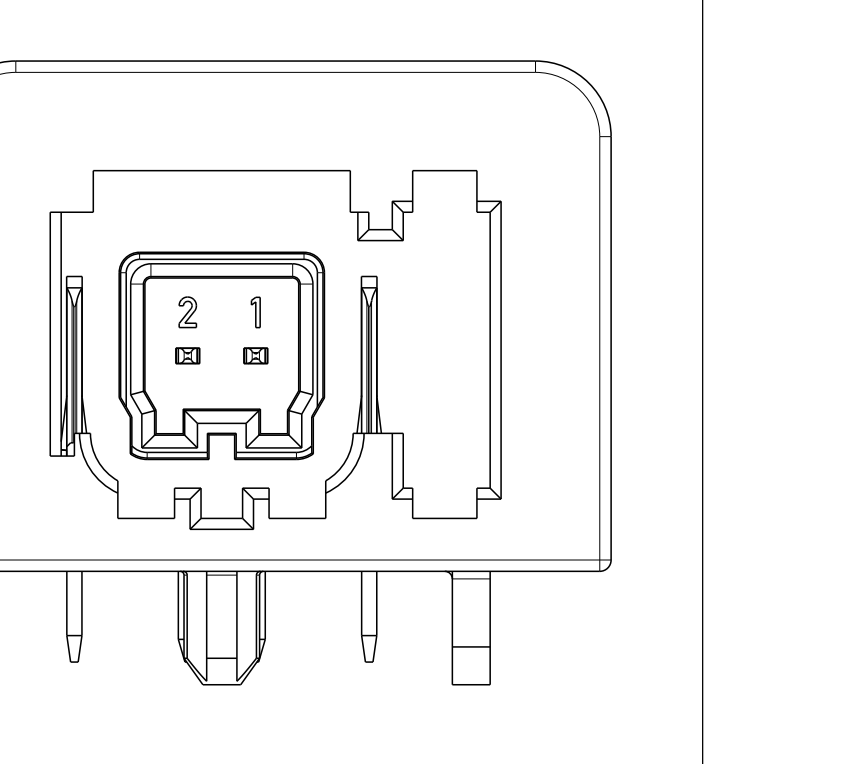
9-2304372-3_COD_C AS SHOWN wie gezeichnet



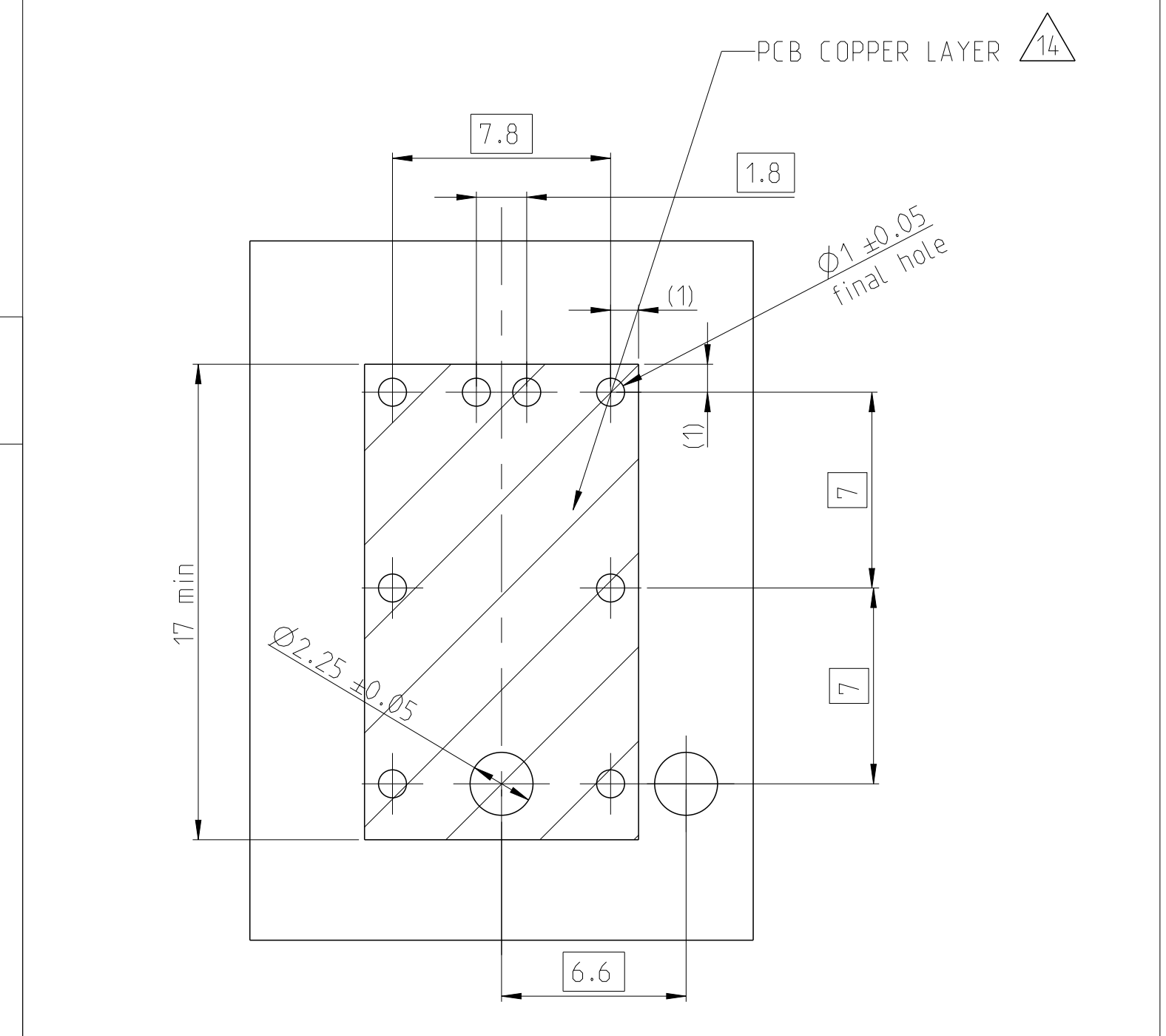
9-2304372-7_COD_J AS SHOWN wie gezeichnet



9-2304372-9_COD_L AS SHOWN wie gezeichnet



RECOMMENDED PCB LAYOUT / EMPFOHLENES PCB LAYOUT
 CUSTOMER IS RESPONSIBLE FOR LAYOUT / KUNDE IST FUER DAS LAYOUT VERANTWORTLICH



REVISIONS				
REV	DATE	DESCRIPTION	BY	APPD
A1	30NOV2016	UPDATE DRAWING	AB	AB
A2	14FEB2017	ADDED SERIES PART	MSA	AB

GENERAL NOTES
 ALLGEMEINE Bemerkungen

- PRESS OUT FORCE FOR NANO MGS >15N WITH FEED RATE 25mm/min
 Kontaktausdruckkraft der Nano MGS Kontakte >15N mit Vorschubgeschwindigkeit 25mm/min.
- INTERFACE ACC. TO 208-18006, REV. A1, 06. JUN 2016
 Schnittstelle nach 208-18006, Rev.A1 vom 06.06.2016
-
- TOLERANCE ACC. TO DIN EN ISO 8015, DIN EN ISO 14405-1
 GENERAL TOL. ACC. TO DIN 16742 TGS, EXCEPT ANGLE DIM. (SEE TITLE BLOCK)
 Tolerierung nach DIN EN ISO 8015, DIN EN ISO 14405-1
 Allgmeintoleranzen nach DIN 16742 TGS, ausser Winkelmasse (siehe Schriftkopf)
- PACKAGING ACC. TO V2304372 TAPE & REEL
 Verpackung nach V2304372 Tape & Reel
-
- CONTACT SURFACE
 MATING SIDE 1-3 µm Sn OVER 1.0-2.2 µm Ni. SOLDER SIDE 3-8µm Sn OVER 1.0-2.2 µm Ni
 Kontaktoberflaeche
 Steckseitig 1-3 µm Sn ueber 1.0-2.2 µm Ni. Loetseitig 3-8µm Sn ueber 1.0-2.2 µm Ni
- VACUM GRIP AREA
 Ansaugflaeche
- PART NO EXCHANGEABLE ACC. TABLE
 Teile Nr. auswechselbar nach Tabelle
- SOLDERING PROCESS: LEAD-FREE REFLOW SOLDERING IN REFERENCE TO JEDEC J-STD-020D
 Loetprozess: Bleifreies Reflowloeten in Anlehnung an die JEDEC J-STD-020D
- HEADER FULFILL RF-REQUIREMENTS UP TO 1GHZ ACC. TE SPEC. 108-94509. ALSO MANDATORY IS A PCB COPPER LAYER ACC. TO TE SPEC. 114-94448
 Der Header erfuehlt die RF-Anforderungen bis zu 1 GHz nach TE Spez. 108-94509. Ebenfalls notwendig ist eine Leiterplatten Kupferschicht nach TE Spec. 114-94448
- HEADER FULFILL RF-REQUIREMENTS UP TO 100 Mhz ACC. TE SPEC 108-94414
 Der Header erfuehlt die RF-Anforderungen bis zu 100MHz nach TE Spez.108-94414
- POSSIBLE FIXTURE OF HEADER WITH THE AGGREGAT CASE
 Moegliche Fixierung des Header durch das Aggregat Gehaeuse
- APPLICATION SPECIFICATION ACC. TO 114-94448
 Anwendungspezifikation TE Spez. 114-94448

TE ORDER NO.	WEIGHT	CODING	REV	QTY.	DESCRIPTION	MATERIAL	POS.
9-2304372-9	2.98	Z	A	2	Nano MGS TAB 90°	Cu-Alloy	3
				2	Shield	Cu-Alloy	2
				1	1 Part 90° HSG COD.Z	PA&T-GF30	1
9-2304372-7	2.98	J	A	2	Nano MGS TAB 90°	Cu-Alloy	3
				2	Shield	Cu-Alloy	2
				1	1 Part 90° HSG COD.J	PA&T-GF30	1
9-2304372-3	2.98	C	A	2	Nano MGS TAB 90°	Cu-Alloy	3
				2	Shield	Cu-Alloy	2
				1	1 Part 90° HSG COD.C	PA&T-GF30	1
9-2304372-2	2.98	B	A	2	Nano MGS TAB 90°	Cu-Alloy	3
				2	Shield	Cu-Alloy	2
				1	1 Part 90° HSG COD.B	PA&T-GF30	1
9-2304372-1	2.98	A	A	2	Nano MGS TAB 90°	Cu-Alloy	3
				2	Shield	Cu-Alloy	2
				1	1 Part 90° HSG COD.A	PA&T-GF30	1

THIS DRAWING IS A CONTROLLED DOCUMENT. DATE: 03JUN2016, BY: J. Burkhard, APPD: J. Burkhard

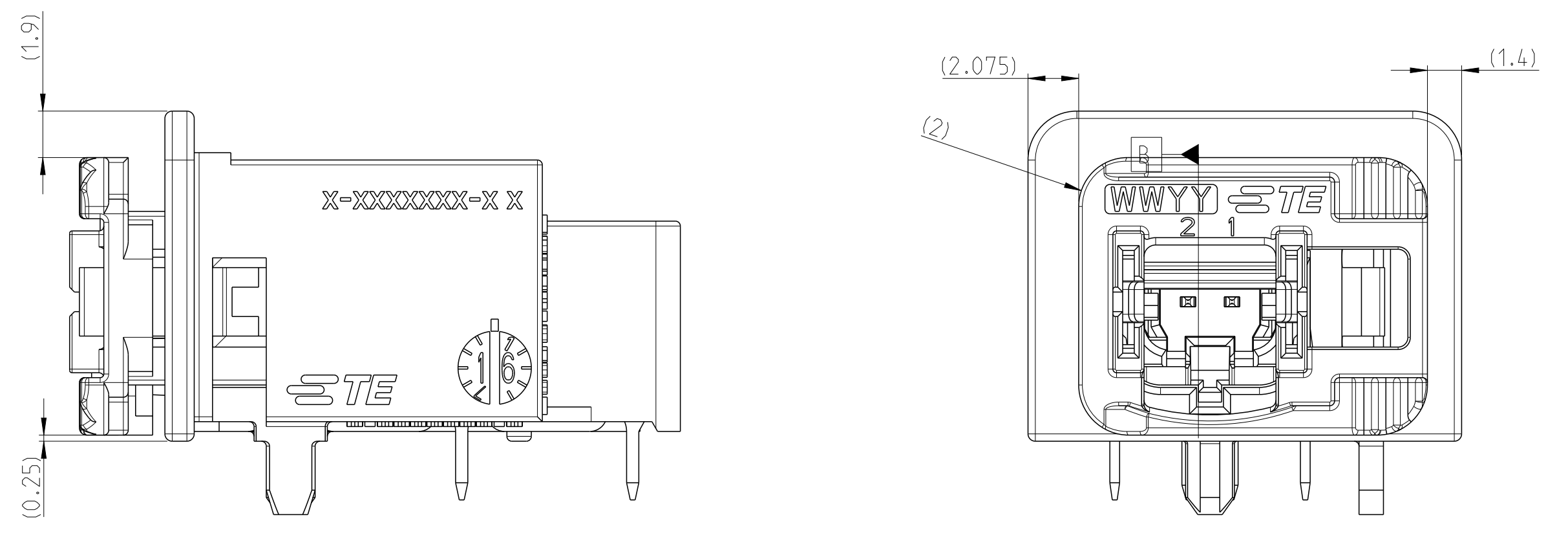
TE Connectivity

1 PORT HEADER ASSY
 1 Part Header ASSY

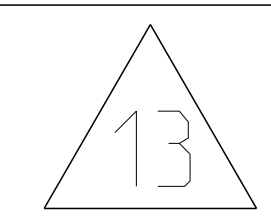
SCALE: 5:1, SHEET: 2 of 3, REV: A2

REVISIONS				
NO.	DATE	DESCRIPTION	BY	APPD.
1		SEE SHEET 1		

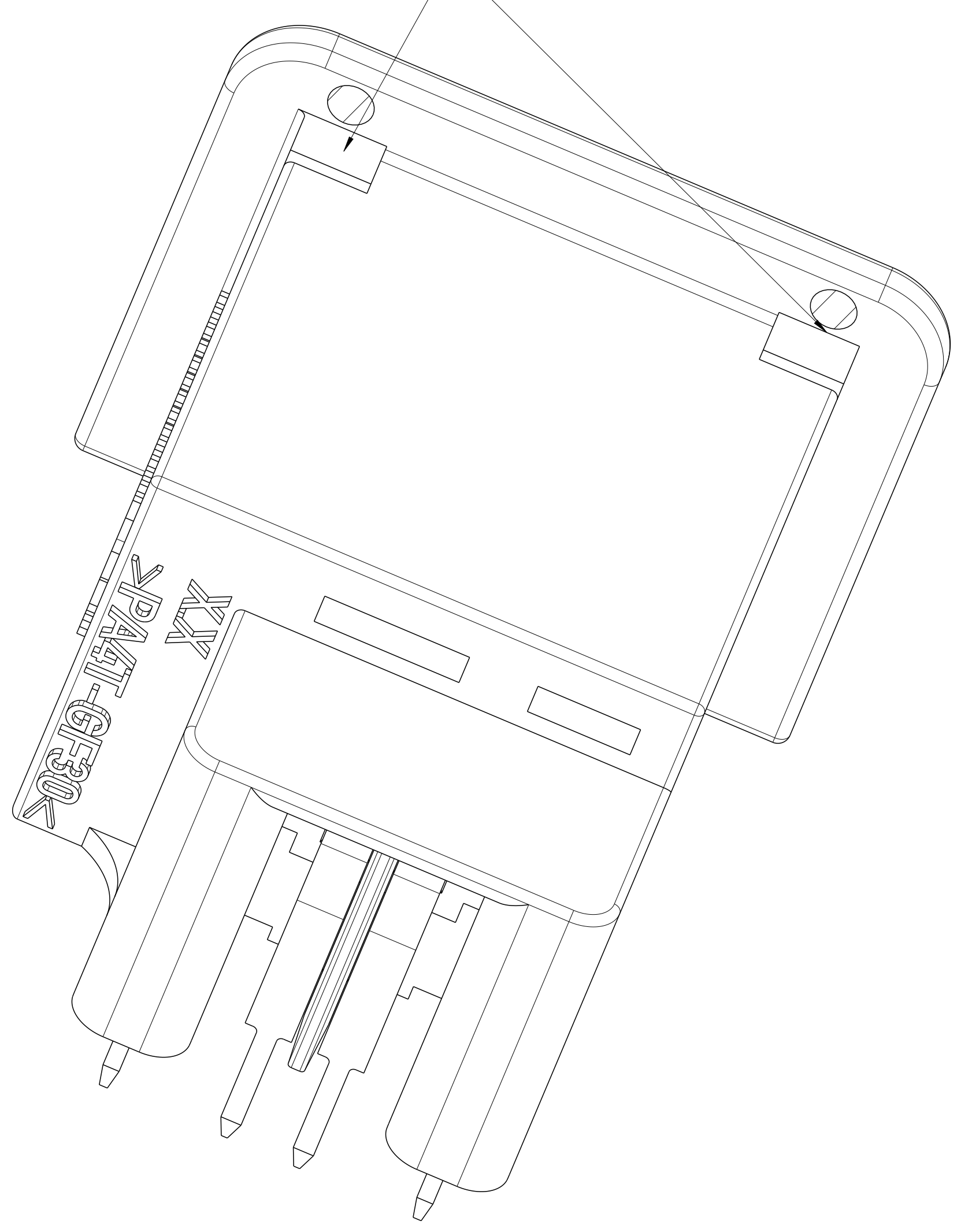
MATED WITH CONNECTOR



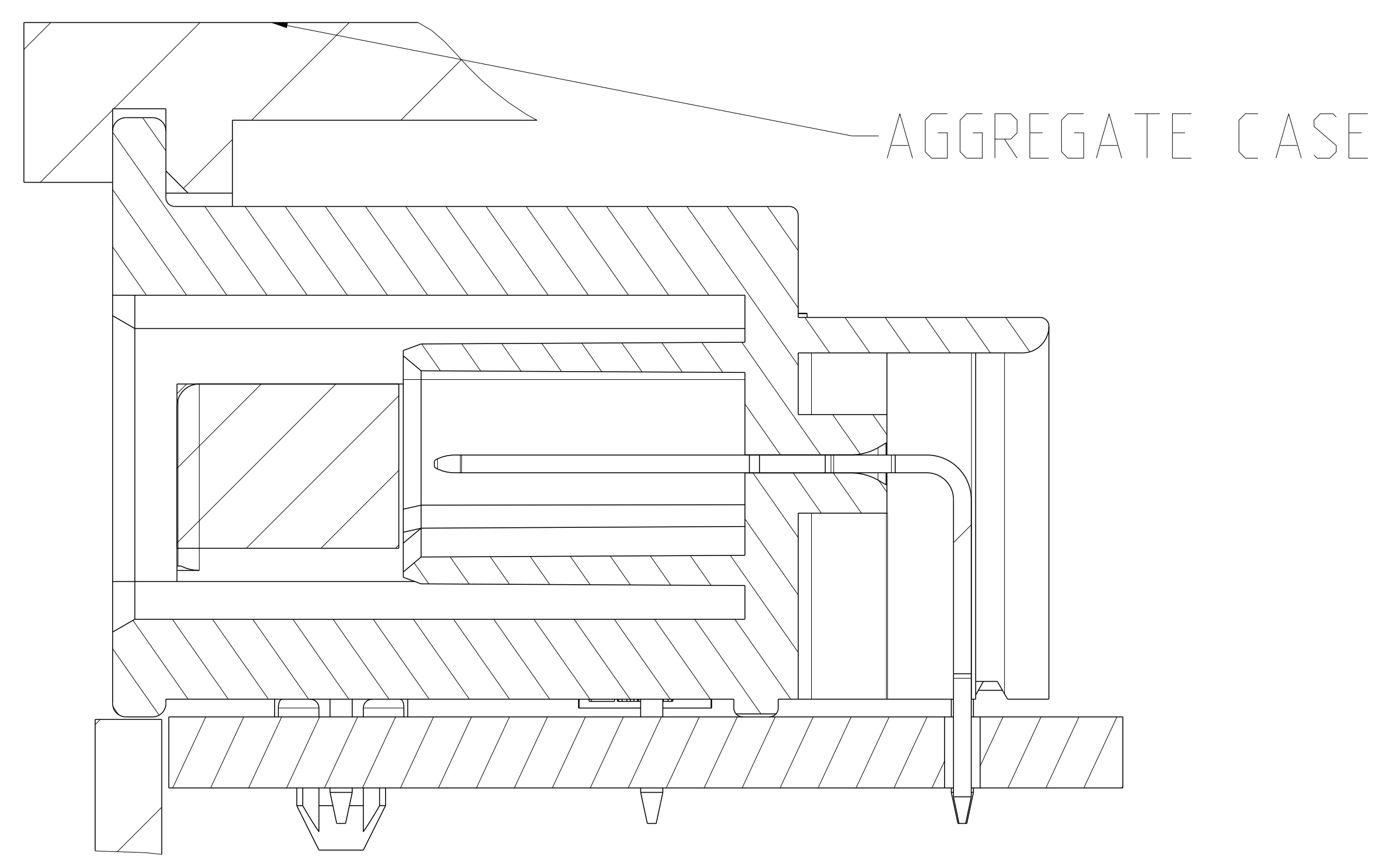
POSSIBLE FIXTURE OF HEADER



CONTACT POINTS FOR AGGREGAT CASE



PROPOSAL CASE



AGGREGATE CASE

THIS DRAWING IS A CONTROLLED DOCUMENT.		DATE	TE Connectivity	
DIMENSIONS:	UNLESS OTHERWISE SPECIFIED:	CHK	APVD	NAME
0 P/LC	mm			PRODUCT SPEC
1 P/LC	mm			APPLICATION SPEC
2 P/LC	mm			
3 P/LC	mm			
4 P/LC	mm			
5 P/LC	mm			
6 P/LC	mm			
7 P/LC	mm			
8 P/LC	mm			
9 P/LC	mm			
10 P/LC	mm			
MATERIAL:	FINISH:	WEIGHT:	SIZE	CASE CODE
			A0	
			SCALE	SHEET OF REV